

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [1] @ 20mA	
			Min.	Typ.
KB2735YW	Yellow (GaAsP/GaP)	White Diffused	12	23

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Yellow	590		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Yellow	588		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Yellow	35		nm	I _F =20mA
C	Capacitance	Yellow	20		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Yellow	2.1	2.5	V	I _F =20mA
I _R	Reverse Current	Yellow		10	uA	V _R =5V

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	
Lead Solder Temperature[2]	260°C For 3-5 Seconds	

Notes:

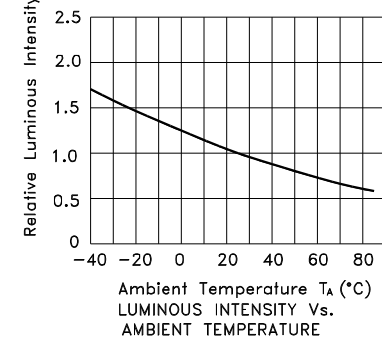
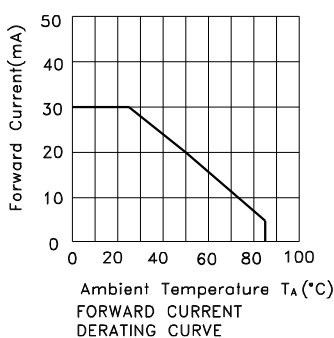
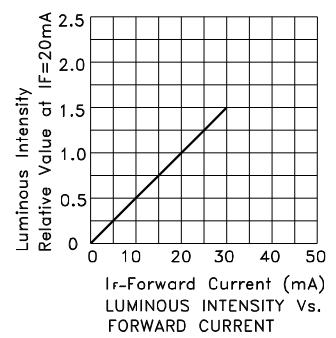
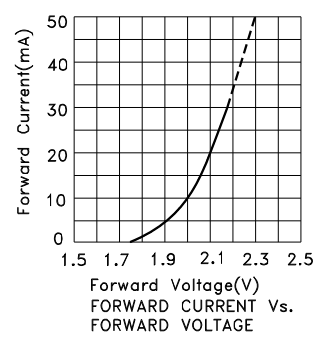
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.



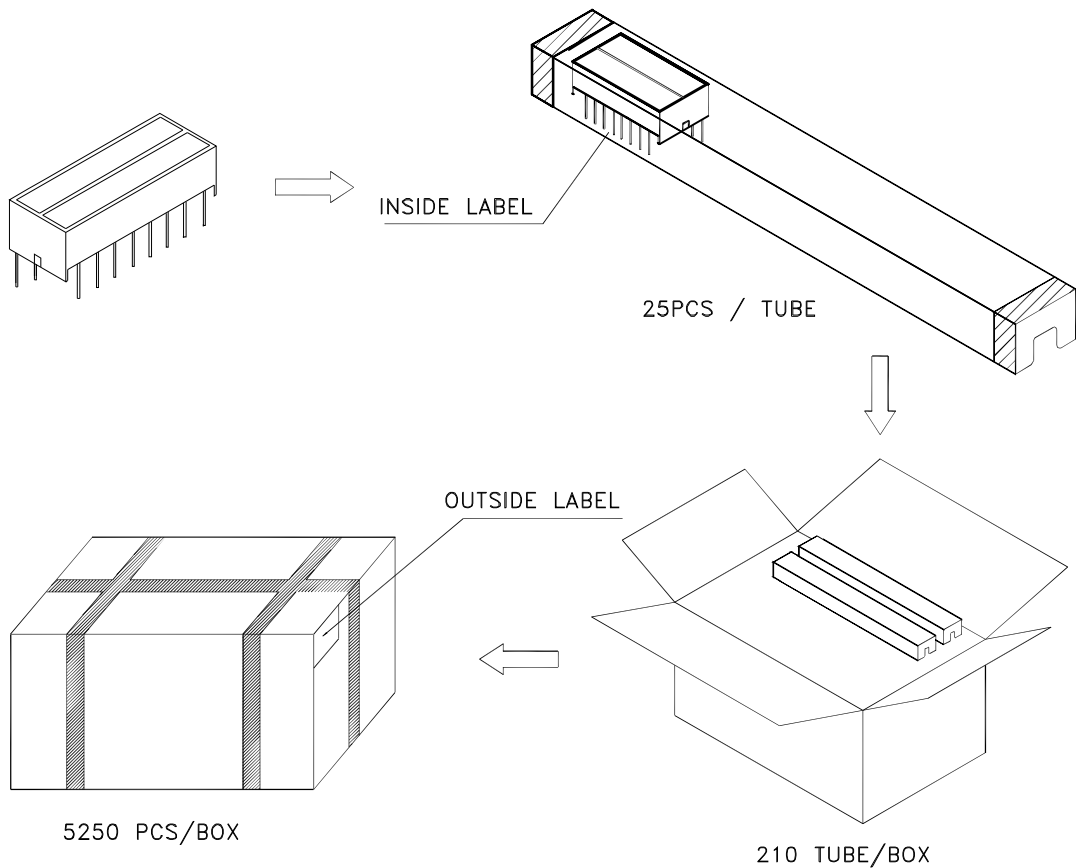
Yellow

KB2735YW



PACKING & LABEL SPECIFICATIONS

KB2735YW



Inside Label On IC-tube

Kingbright	TYPE: KB2735xxx	PASSED xx xx xx FQCX	Date
	QTY: 25 PCS CODE: xx		Number OF FQC
XXXXXXXXXX-XXXX		RoHS Compliant	
LOT NO.			

Outside Label On Box

XXXXXX	Bin Code		Number OF QA
KB2735xxx	XX	QAx xx xx xx PASSED	Date
5250 PCS			RoHS Compliant

THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools.
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



Installation

- 1.The installation process should not apply stress to the lead terminals.
- 2.When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top-surface temperature should be kept below 105°C
- 5.No more than once.

Soldering General Notes:

- a. Through-hole displays are incompatible with reflow soldering.
- b. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

1. Mild "no-clean" fluxes are recommended for use in soldering.
2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts. And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

1. Protective current-limiting resistors may be necessary to operate the Displays.
2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.



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